*** Required Field**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and checkboxes will appear below. Check all applicable exemptions.

1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.

2a. Mercury in straight fluorescent lamps for general purposes not exceeding 10 mg. in halophosphate lamps

2b. Mercury in straight fluorescent lamps for general purposes not exceeding 5 mg. in triphosphate lamps with a normal lifetime

2c. Mercury in straight fluorescent lamps for general purposes not exceeding 8 mg. in triphosphate lamps with long lifetime

3. Mercury in straight fluorescent lamps for special purposes.

4. Mercury in other lamps not specifically mentioned in this list.

5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.

6a. Lead as an alloying element in steel containing up to 0.35% lead by weight.

6b. Lead as an alloying element in aluminum containing up to 0.4% lead by weight.

6c. Lead as an alloying element in copper containing up to 4% lead by weight.

7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).

7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications.

7c. Lead in electronic ceramic parts (e.g. piezoelectronic devices).

8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations piezoelectronic devices).

9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators

10a. Deca BDE in polymeric applications

10b. Lead in lead/bronze bearing shells and bushes

11. Lead used in compliant pin connector systems.

12. Lead as a coating material for a thermal conduction module c-ring.

13a. Lead in optical and filter glass.

13b. Cadmium in optical and filter glass.

14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight .

15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

*** Required Field**
